Innovative products cited in U.K.

Dowty Electronic Interconnect was given a product innovation award at INTERNEPCON/UK85 for its Chiprack, an interconnecting system for VLSI chips. Chiprack is shown here next to a British 50-pence coin, about the size of a U.S. quarter.

Mike Anstey: pioneered 3-D circuitry.

Brighton, England — Awards were presented to three British companies Electro-Mechan ... ognition of outstanding product inno- ... vations. "Most Innovative Electro-Mechani- ... cal Product" was garnered by Dowty Electronic Interconnect, a unit of I.C.D.C.'s Dowty Electronic Compo- nents located in High Wycombe, Bucks. Their winner was "Chiprack," a modular, three-dimensional system for interconnecting VLSI devices pack- aged in leadless chip carriers.

Patent: 4,638,348 Jan. 20, 1987

United States Patent [19]

Space saving – 3-D modular connector system

Imagine a connector system that will allow you to put the contents of a single eurocard onto a pcb less than a quarter of the area; that makes parallel processing simple and faster; is easy to upgrade and add to; and finally that makes diagnostics and testing a doddle. These are some of the claims for Dowty Interconnect's Chiprack. Project manager Ron Wilkins see its potential as a follow on from traditional, bus based products – "Industry has given engineers the chan ... develop their own chips, now they have the possibil ... designing their own chip computer using Chiprack." Chris Evans-Pugbe went to Dowty Interconnect's Lo ... centre to find out more.

Chiprack has been slowly going through development since 1984. Inventor, Mike Anstey, introduced the system to Dowty who took up the idea for development. Anstey now works with Dowty on a consultancy basis and meeting the ... the high r ... Burke believ ... rent SMD ... board will be ... next five yea ...

ELECTRONICS PACKAGING

ELECTRONIC PRODUCTION—March 1989

...titioning—The ...rack Solution

... of partitioning large electronic ...y using interconnected stacks has ...loped by Dowty Interconnect. A ...loying the technology, known as ...rack system, is described by *Mike Anstey.*

...ERENCE PREVIE...

...ems

In so far as avionics is concerned Burke looks to an answer from the hybrid manufacturers and in the construction of complete circuits rather than parts of circuits.

He also looks towards the possibility of further integration with three dimensional circuitry similar to that pioneered by Mike Anstey of ICDC.

CHIP RACK, the first three-dimensional racking system for the interconnection of VLSI chips, made its debut at the Royal Society last week. A working prototype, carrying the Chip Rack was shown to ... Anstey, claims that the system is far superior to the traditional printed circuit board for connecting advanced VLSI circuitry. Once designers become used to designing on to silicon, much of the complexity of interconnection ... orporated ...

...Dowty buys into computer brainwave

...ews Feature

£250,000 cash for chip connector

A UK firm, Ultra Electronic Components, is out to change the face of basic computer building blocks. It has invested £250,000 in research on the Chip Rack, a compact chip connecting system.

Perhaps the most exciting development in electronic circuitry area is the Chip Rack. Enables microchips to be interconnected vertical racks. Air circulating around chip improves thermal management allowing more microprocessor capability.

By Peter Large, Technology Correspondent

A WAY of teaming microchips that might make the multi-dimensional computer commonplace has been thrown up by the Dowty group in £250,000 research investment.

Patent Number: 4,502,098

Date of Patent: Feb. 26, 1985

[45]

Mike Anstey: ... circuitry.

INTERCONNECTION

[11] 4,381,456

[45] Apr. 26, 1983

PATENT

...4: G06F 13/00

project. The company ... take it on and cont... patenting process but, ... a US patent was ... straight away, the U... suffered a series of d... will only be granted ... Their most interest... tion is the Chip ... because it relies on ... change of thinking ... interconnection ... industry, it will fac... struggle to be accep... Dowty Electro... connect, howe... sufficient faith in ... acquire the manuf... development righ... invested £250 000 ... "The idea beh... changes in th... electronics comp... from discrete c... vlsi devices, m... whole method ... using pcbs can ... said Anstey.

1. I am writing to inform you under Section 18(4) ... reported that your patent application number 8321375 ... of the Act and Rules. Your application is therefore granted